Page 2 Dkt: 303.601US3

AMENDMENT AND RESPONSE UNDER 37 C.F.R § 1.111 Serial Number:10/722,838

Filing Date: November 26, 2003
Title: METHOD OF PACKAGING AT A WAFER LEVEL USING AN ADHESIVE (as amended)

IN THE TITLE

Please amend the title as follows:

METHOD OF PACKAGING AT A WAFER LEVEL USING AN ADHESIVE